Enrique Miranda was born in Buenos Aires, Argentina in 1963. He received a PhD in Electronics Engineering from the Universitat Autònoma de Barcelona (UAB), Spain (1999) and a PhD in Physics from the Universidad de Buenos Aires (UBA), Argentina (2001). From 1987 to 2003, he was Assistant Professor at the Faculty of Engineering - UBA, and from 2001 to 2005, Associated Researcher of the Consejo Nacional de Investigaciones Científicas y Técnicas (CONICET), Argentina. Since 2006, he is Professor at the Escola Técnica Superior d'Enginyeria - UAB. Dr. Miranda has received research fellowships from the UBA (as student and graduate), INTERCAMPUS (Universidad de Zaragoza) and MUTIS (UAB) from the Spanish International Cooperation Agency, from the German Exchange Academic Agency (Technical University Hamburg-Harburg), from the italian government (Universita degli Studi di Padova), RAMON y CAJAL (UAB) from the Ministerio de Ciencia y Tecnología, Spain, MATSUMAE (Tokyo Institute of Technology) from the Matsumae International Foundation, Japan, and TAN CHIN TUAN from the Nanyang Technological University, Singapore. In 2008, Dr. Miranda received the WALTON awards from the Science Foundation Ireland. He has authored and co-authored more than 80 papers in international journals, most of them devoted to the electron transport problem through the gate insulator in MOS devices under different circumstances: direct and Fowler-Nordheim tunneling, effects of trapped charge, stress-induced leakage current and post-breakdown conduction. Dr. Miranda serves as member of the Distinguished Lecturer program of the Electron Devices Society (EDS-IEEE) and is reviewer of IEEE Trans. on Electron Devices, IEEE Electron Devices Letters, Journal of Applied Physics, Applied Physics Letters, Thin Solid Films, Microelectronics Engineering and Microelectronics Reliability. He also belongs to the Editorial Advisory Board of the latest journal. Dr. Miranda has served in the technical committees of Insulating Films on Semiconductors (INFOS'07 and '09), IEEE International Reliability Physics Symposium (IRPS'08 and '09) and in the advisory committee of IEEE International Symposium on the Physical and Failure Analysis of Integrated Circuits (IPFA'09). He has been Guest Editor in Microelectronics Reliability, Vol. 12, Issue 15, 2005 and has achieved the best oral paper at the 26th International Conference on Microelectronics, Serbia, 2008.